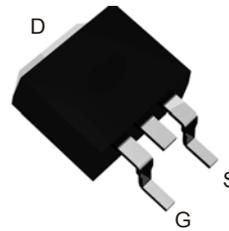
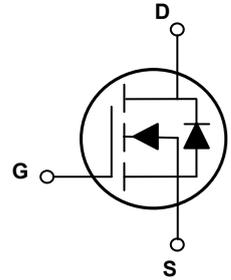


## Main Product Characteristics

$BV_{DSS}$	80V
$R_{DS(ON)}$	2.0m $\Omega$ (Max.)
$I_D$	298A



TO-263 (D<sup>2</sup>PAK)



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery

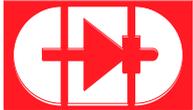


## Description

The GSGT08298 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	80	V
Gate-Source Voltage	$V_{GS}$	±20	V
Drain Current-Continuous	$I_D$	298	A
Drain Current-Continuous (T <sub>C</sub> =100°C)		208	A
Pulsed Drain Current	$I_{DM}$	1192	A
Maximum Power Dissipation	$P_D$	330	W
Derating Factor		2.2	W/°C
Single Pulse Avalanche Energy <sup>1</sup>	$E_{AS}$	2228	mJ
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.45	°C/W
Thermal Resistance, Junction-to-Ambient <sup>4</sup>	$R_{\theta JA}$	40	°C/W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To +175	°C

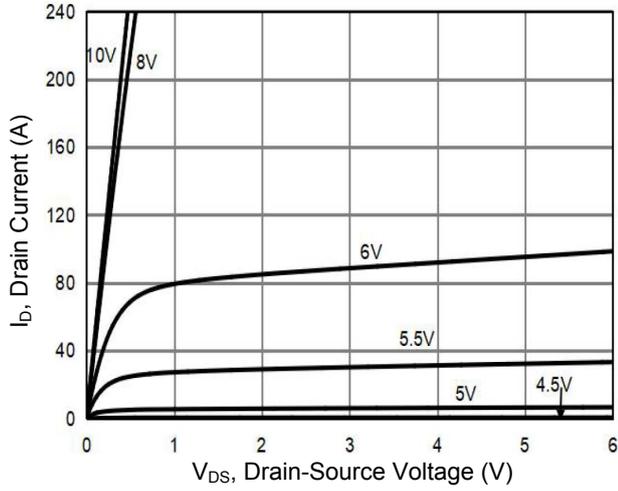

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	80	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.5	3.5	4.5	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	1.6	2.0	m $\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=20A$	-	70	-	S
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=40V, V_{GS}=0V, F=1.0MHz$	-	9256	-	pF
Output Capacitance	$C_{oss}$		-	4424	-	
Reverse Transfer Capacitance	$C_{rss}$		-	128	-	
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$	$V_{DD}=40V, I_D=20A, V_{GS}=10V, R_G=3\Omega$	-	27.2	-	nS
Turn-On Rise Time <sup>2</sup>	$t_r$		-	21.3	-	
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$		-	56.6	-	
Turn-Off Fall Time <sup>2</sup>	$t_f$		-	25	-	
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{DS}=40V, I_D=20A, V_{GS}=10V$	-	136	-	nC
Gate-Source Charge <sup>2</sup>	$Q_{gs}$		-	37	-	
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$		-	30	-	
<b>Drain-Source Ratings and Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=20A$	-	-	1.2	V
Diode Forward Current	$I_S$	-	-	-	298	A
Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C, I_F=20A, di/dt=100A/\mu s$	-	115.2	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	333	-	nC

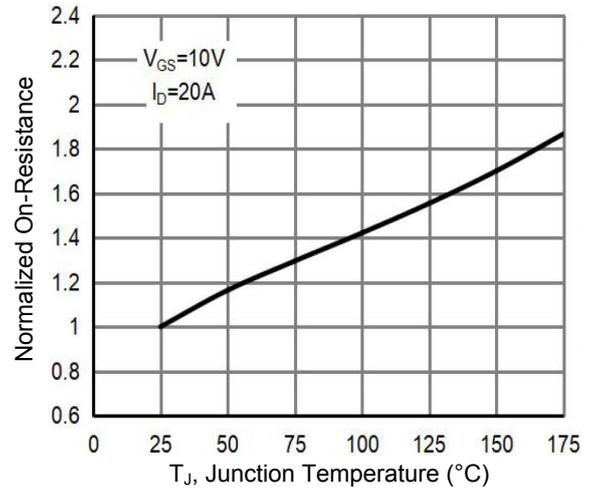
## Notes:

- $E_{AS}$  condition:  $T_J=25^\circ C, V_{DD}=40V, V_G=10V, L=0.5mH, R_G=25\Omega$
- Guaranteed by design, not subject to production
- These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(MAX)}=175^\circ C$ . The SOA curve provides a single pulse rating.
- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. copper, in a still air environment with  $T_A=25^\circ C$ . The maximum allowed junction temperature of 175 $^\circ C$ . The value in any given application depends on the user's specific board design.

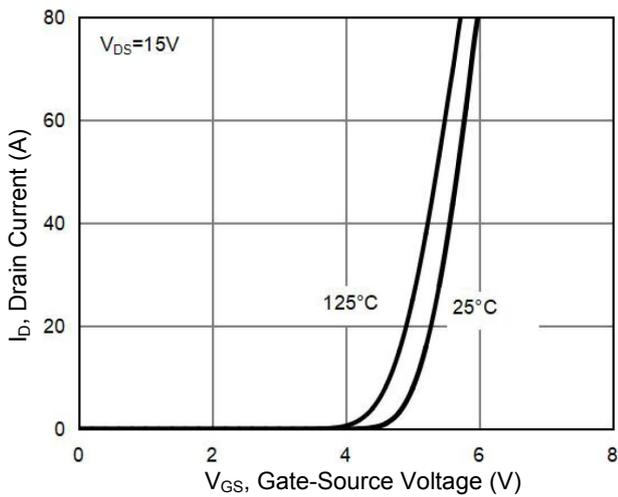
**Typical Electrical and Thermal Characteristic Curves**



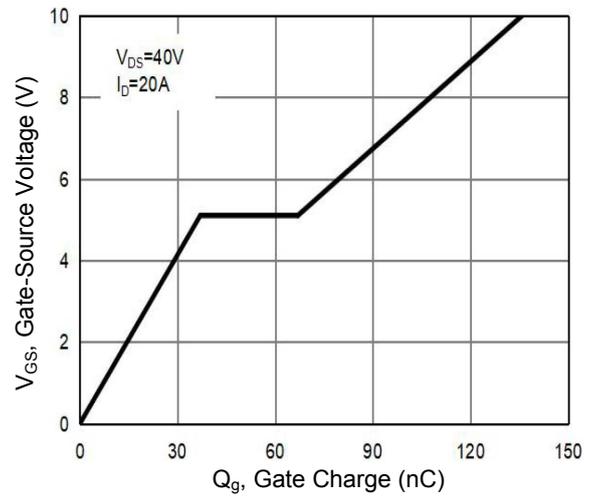
**Figure 1. Output Characteristics**



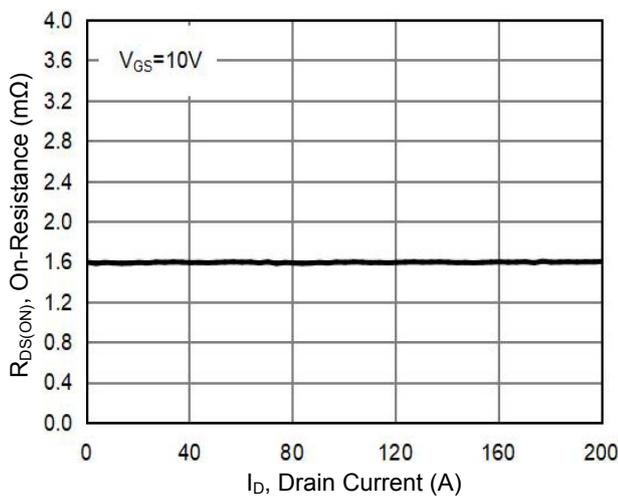
**Figure 2.  $R_{DS(ON)}$  vs. Junction Temperature**



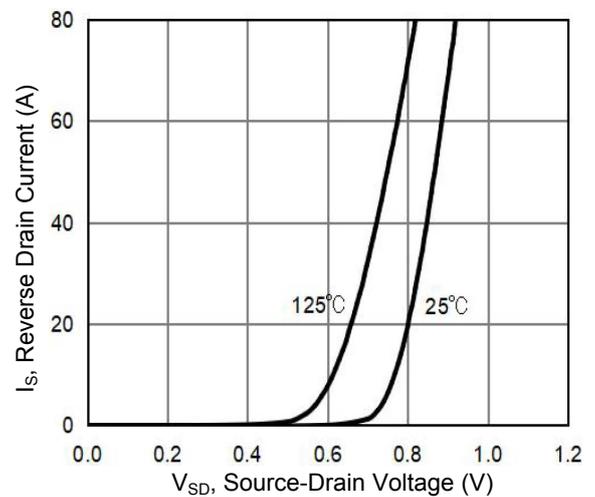
**Figure 3. Transfer Characteristics**



**Figure 4. Gate Charge**

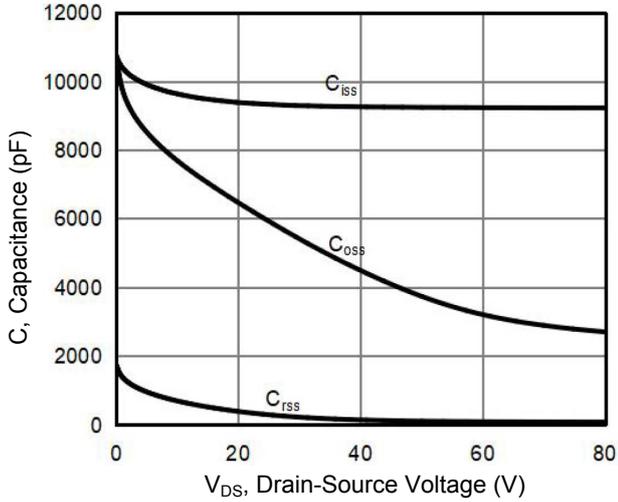


**Figure 5.  $R_{DS(ON)}$  vs. Drain Current**

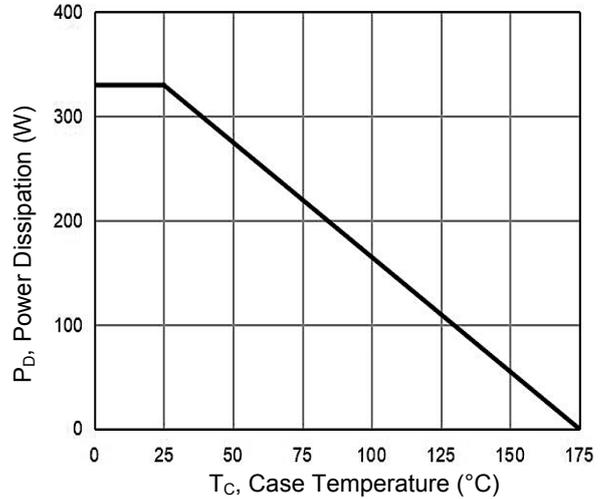


**Figure 6. Source-Drain Diode Forward Voltage**

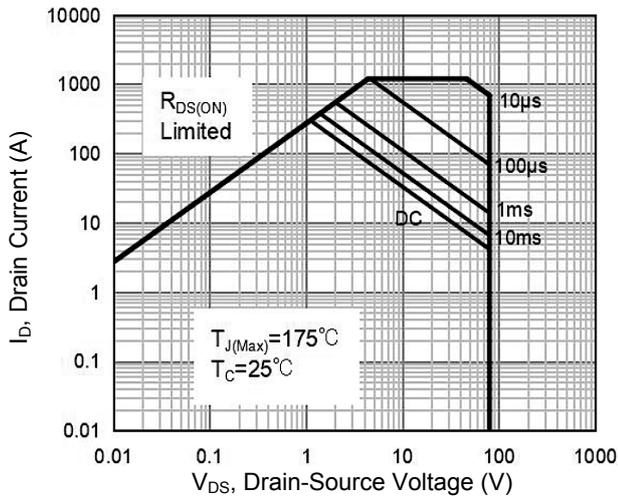
**Typical Electrical and Thermal Characteristic Curves**



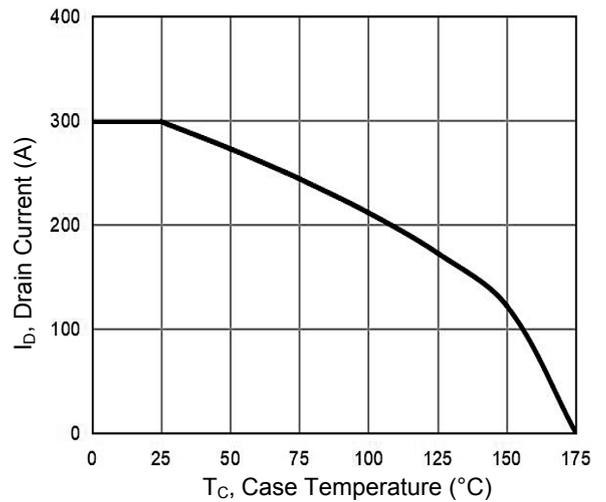
**Figure 7. Capacitance vs.  $V_{DS}$**



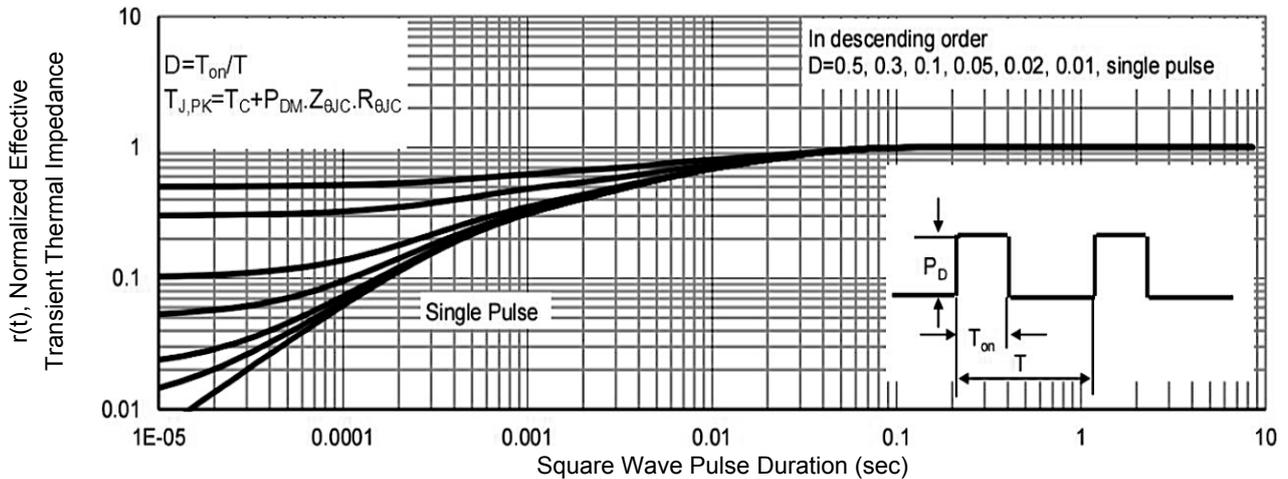
**Figure 8. Power De-Rating**



**Figure 9. Safe Operation Area<sup>3</sup>**

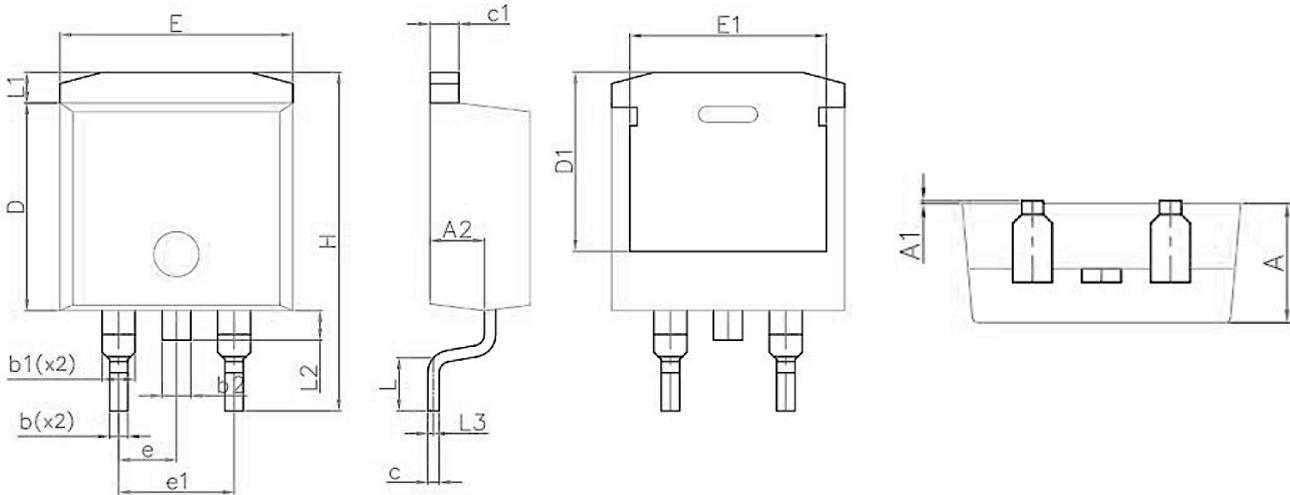


**Figure 10. Current De-Rating**



**Figure 11. Normalized Maximum Transient Thermal Impedance**

**Package Outline Dimensions TO-263 (D<sup>2</sup>PAK)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.20	4.60	0.165	0.181
A1	0.00	0.25	0.000	0.010
A2	2.20	2.60	0.087	0.102
b	0.70	0.90	0.028	0.035
b1	1.20	1.75	0.047	0.069
b2	1.17	1.37	0.046	0.054
c	0.40	0.60	0.016	0.024
c1	1.15	1.40	0.045	0.055
D	9.10	9.30	0.358	0.366
D1	7.63	8.23	0.300	0.324
E	10.05	10.45	0.396	0.411
E1	8.35	8.95	0.329	0.352
e	2.54 BSC		0.100 BSC	
e1	5.08 BSC		0.200 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	1.36 REF		0.054 REF	
L2	1.30 REF		0.051 REF	
L3	0.25 REF		0.010 REF	

**Order Information**

Device	Package	Marking	Packaging	SPQ
GSGT08298	TO-263 (D <sup>2</sup> PAK)	T08298	Tape & Reel	800 Pcs / Reel